SM switch Co.,Ltd.
无锡斯茂科技有限公司
ISO 9001/ISO14001

- 规 格 书 -

产品型号：MER-08-WB（thin）

产品名称：旋转编码开关

SM SWITCH CO.,LTD

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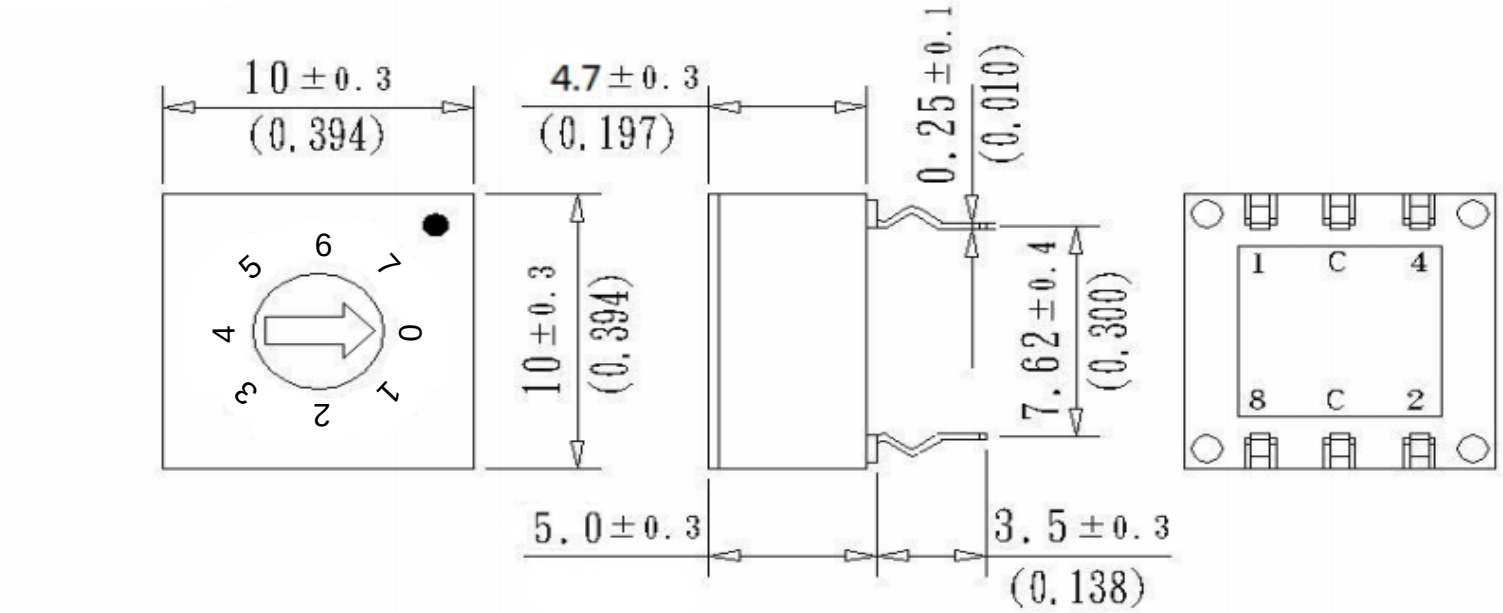
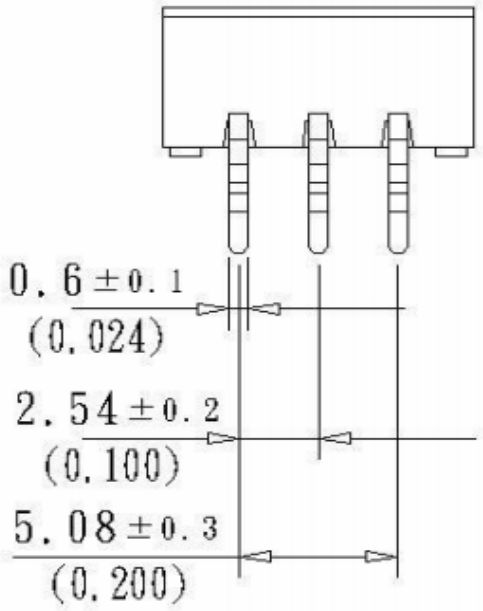
MARK	DATE	REMARKS
⚠		
⚠		

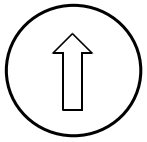




		Real Code				
		C	1	2	4	8
8 Position / 6 Position	0	●				
	1	●	●			
	2	●		●		
	3	●	●	●		
	4	●			●	
	5	●	●		●	
	6	●		●	●	
	7	●	●	●	●	

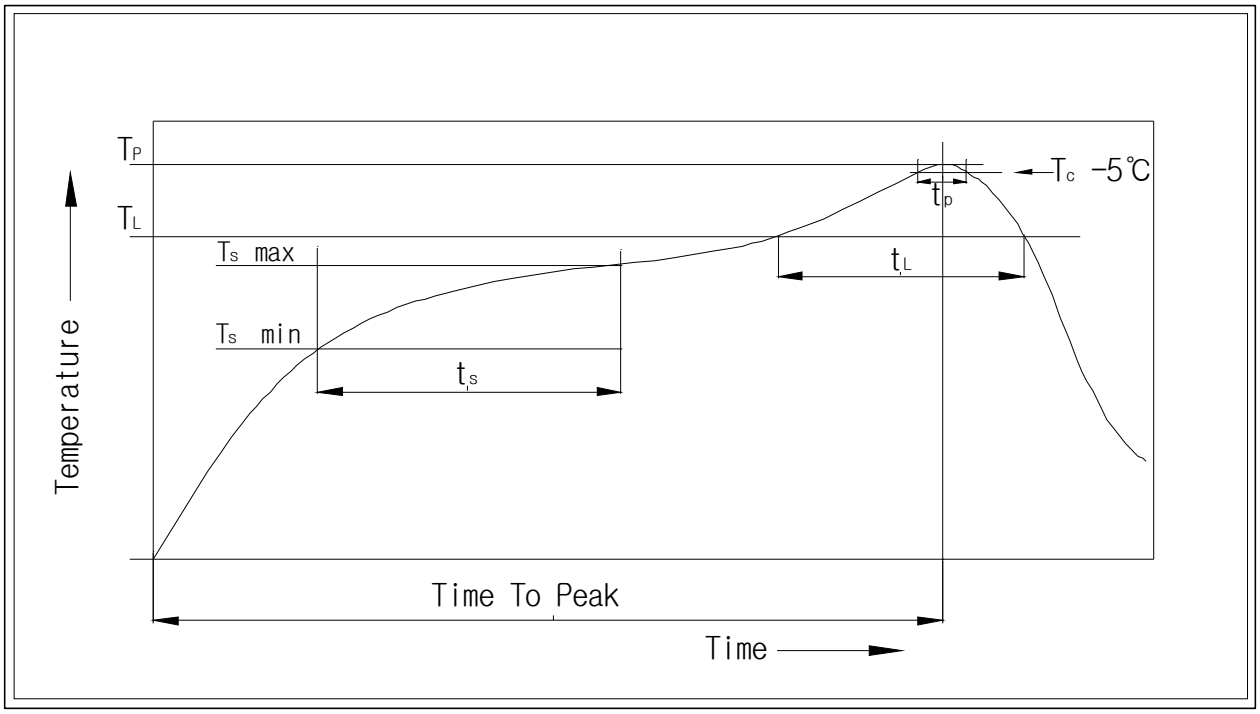
APPD	CHKD	D'SGD	TITLE. ROTARY DIP SWITCH	
Y.D WANG	J.S KIM	H.S LEE	MODEL NO. MER-08-WB (thin)	REV A
			SM SWITCH CO., LTD.	

1. Style:
   This specification describes "Rotary Switch"mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.
   1.1 Operating / Storage Temperature Range : -40℃ ~ +85℃
2. Current Range:
   2.1 None-Switching : 200 mA, 42V
   2.2 Switching : 150 mA, 42V
3. Type of Actuation : Rotating
4. Test Sequence :

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
ELECTRIC PERFORMANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product
	2	Contact Resistance	① To be measured between the two terminals associated with each switch pole ② Measurements shall be made with a 1kHz shall current contact resistance meter	80mΩ max.(initial)
	3	Insulation Resistance	250V DC, 1minute ±5seconds	100MΩ min
	4	Dielectric withstanding Volotage	250V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame For 1 minute	There shall be no breakdown or flashover
	5	Operation Force	Applied in the direction of operation 	700gf/cm. max

MACHIN PERFORMANCE	6	Operation Life	Measurements shall be made following the test set forth below: 1)150mA, 42V DC resistive load 2)Rate of operation: 15~20 cycles/ minute 3)Step of operation: 10,000 steps	1)As shown in item 3,4 2)Contact Resistance: 200mΩ max 3)Final-after test
	7	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -60℃ ±3℃ 2)Time: 96 hours	1)As shown in item 3~5 2)Contact Resistance: 200mΩ max
	8	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 125℃ ±2℃ 2)Time: 96 hours	1)As shown in item 3~5 2)Contact Resistance: 200mΩ max
	9	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40℃ ±2℃ 2)Relative humidity: 90~95% 3)Time: 96 hours	1)As shown in item 4 2)Contact Resistance: 200mΩ max 3)Insulation Resistance: 10MΩ min

6. Reflow Soldering Conditions:



1) Classification Reflow Profiles

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Ts max to T_P)	3℃/second max
Preheat - Temperature Min(Ts min) - Temperature Max(Ts max) - Time (ts min to ts max)	 150℃ 200℃ 60-100seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	 217℃ 60-100seconds
Peak/Classification Temperature(T_P)	240~260℃ +0℃/ -5℃
Time within 5℃ of actual Peak Temperature(t_P)	min 30 seconds
Ramp-Down Rate	6℃/sec max
Reflow Soldering	260℃/4~5 seconds max

7. This item is "ROHS" Compliant

8. Part List

NO	PART NAME	Q'TY	MATERIALS	TREATMENT	REMARK
1	COVER	1	PA9T		
2	BASE	1			
3	ACTUATOR	1	PA9T		
4	CONTACT & TERMINAL	1	PHOSPHOR BRONZE	CONTACT AND TERMINAL PLATING: GOLD PLATING OVER NICKEL TINNING	Au 0.03μm Min Ni 0.1μm Min TIN 0.1μm Min
5	PCB	1	EPOXY	PLATING: GOLD PLATING	Au 0.05μm Min
6	O-Ring	1	SILICONE		